

MB05S THRU MB10S

Features

- Glass Passivated Die Construction
- Low leakage
- Ideal for printed circuit board
- Surge overload rating-35A peak
- Designed for Surface Mount Application
- Plastic Material-UL Flammability 94V-0

Mechanical Data

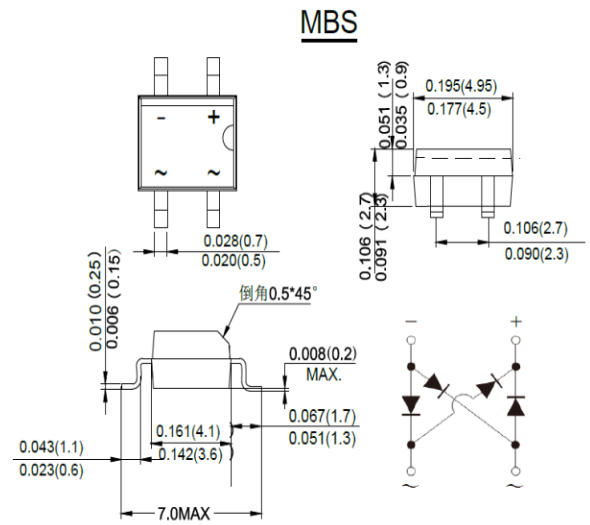
Case: Reliable low cost construction
utilizing molded plastic technique

Terminals: Plated Leads Solderable per
MIL-STD-202, Method 208

Polarity: As Marked on Case

Mounting Position: Any

Marking: Type Number



dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified
Single phase, half wave, 60Hz, resistive or inductive load
For capacitive load, derate current by 20%

TYPE NUMBER	SYMBOL	MB05S	MB1S	MB2S	MB4S	MB6S	MB8S	MB10S	UNITS
Peak Repetitive Reverse Voltage	V_{RRM}								
Working Peak Reverse Voltage	V_{RWM}	50	100	200	400	600	800	1000	V
DC Blocking Voltage	V_{DC}								
RMS Reverse Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1)@ $T_C=100^\circ\text{C}$ (Note 2)@ $T_C=100^\circ\text{C}$	$I_{F(AV)}$				0.5 0.8				A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}				30				A
Forward Voltage per element @ $I_F=0.5\text{A}$ @ $I_F=1.0\text{A}$	V_{FM}				0.95 1.0				V
Peak Reverse Current @ $T_A=25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A=125^\circ\text{C}$	I_R				5.0 200				μA
Typical Thermal Resistance per leg	$R_{\theta JA}$				60				$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}				-55to+150				$^\circ\text{C}$

Note: 1. Mounted on glass epoxy PC board with 1.3mm² solder pad.

2. Mounted on aluminum substrate PC board with 1.3mm² solder pad.

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Characteristic Curves

